

pad, said upper and lower surfaces of said die attach pad being located on opposite sides of said die attach pad;

a plurality of bond wires each coupling one of said conductive leads to a corresponding bonding pad on said semiconductor die; and

a plastic encapsulation enclosing said semiconductor die, said bond wires and said lead frame, exposing a lower surface of said plastic encapsulation said lower surface of said die attach pad and said lower surfaces of said conductive leads.

12. An integrated circuit package as in Claim 11, further comprising a solder ball attached to each of said exposed lower surface of said conductive leads.

13. An integrated circuit package as in Claim 11, further comprising an adhesive pad removably attached to said integrated circuit package, covering said lower surface of said die attach pad and said lower surfaces of said conductive leads.

14. An integrated circuit package as in Claim 13, wherein said integrated circuit package is one of a plurality of integrated circuit packages fabricated simultaneously from said lead frame, said lead frame comprising an array of die attach pads and conductive leads, and wherein said adhesive pad supports die attach pads and said conductive leads prior to singulation of said plurality of integrated circuit packages.

15. An integrated circuit package as in Claim 14, wherein said lead frame is fabricated on a metal panel.

16. An integrated circuit package as in Claim 15, further comprising an encapsulant dam provided to enclose said array of die attach pads and conductive leads.

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